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## **Indium Corporation Presents Cost-Effective Copper Sinter Solutions for Power Electronics at APEC 2026**

CLINTON, N.Y., March 18, 2026 — [Indium Corporation](http://www.indium.com)® Product Manager – Semiconductor [Dean Payne](#) will present copper sinter paste solutions that deliver high thermal and reliability performance, while addressing power electronics cost pressures at APEC 2026, March 22-26, in San Antonio, Texas.

The presentation, *Sinter Pastes for Industry Standard and State-of-the-Art Power Electronics Assembly*, will demonstrate that as cost-reduction demands increase across the industry, copper sinter pastes offer thermal and electrical performance comparable to silver at a lower expense. Case study solutions discussed include pressureless copper sinter for discrete SiC TO-247 packages and pressure-assisted pastes for SiC die-attach on ceramic substrates, and large-area heat-sink attachment in advanced high-power electronics applications.

Dean Payne is responsible for driving profitable growth of Indium Corporation's power semiconductor materials, which include high-Pb die-attach paste, high-temperature Pb-free solutions, and sintering materials. Payne collaborates with internal departments, including sales, technical service, R&D, production, and quality, providing support for all semiconductor and advanced assembly materials.

APEC 2026 visitors can attend Payne's presentation on Wednesday, March 25, at 12:00 p.m. CST. To learn more about Indium Corporation's power electronics and solder solutions, visit [indium.com](http://www.indium.com) or meet with our experts at APEC booth #1553.

### **About Indium Corporation**

Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit [www.indium.com](http://www.indium.com) or email [jhuang@indium.com](mailto:jhuang@indium.com). You can also follow our experts, From One Engineer To Another® (#FOETA), at [www.linkedin.com/company/indium-corporation/](https://www.linkedin.com/company/indium-corporation/).

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